

LEADFRAME AND METHOD FOR REDUCING MOLD COMPOUND ADHESION
PROBLEMS

ABSTRACT OF THE DISCLOSURE

An integrated circuit leadframe has a pair of leadframe rails that are specially treated to adhere to injection mold compounds to a lesser or greater degree than portions of the leadframe rails outside of the treated areas. By adhering to mold compounds to a greater degree, mold compound not removed during a deflashing procedure does not flake off to form mold compound debris during a trimming and forming procedure. By adhering to mold compounds to a lesser degree, substantially all of the mold compound is removed during the deflashing procedure so there is no mold compound to flake off to form mold compound debris during the trimming and forming procedure. The leadframe rails may be treated by forming apertures in the rails, by increasing or decreasing the roughness of the leadframe rails, or by coating the leadframe rails with an adhesion promoting or reducing material.